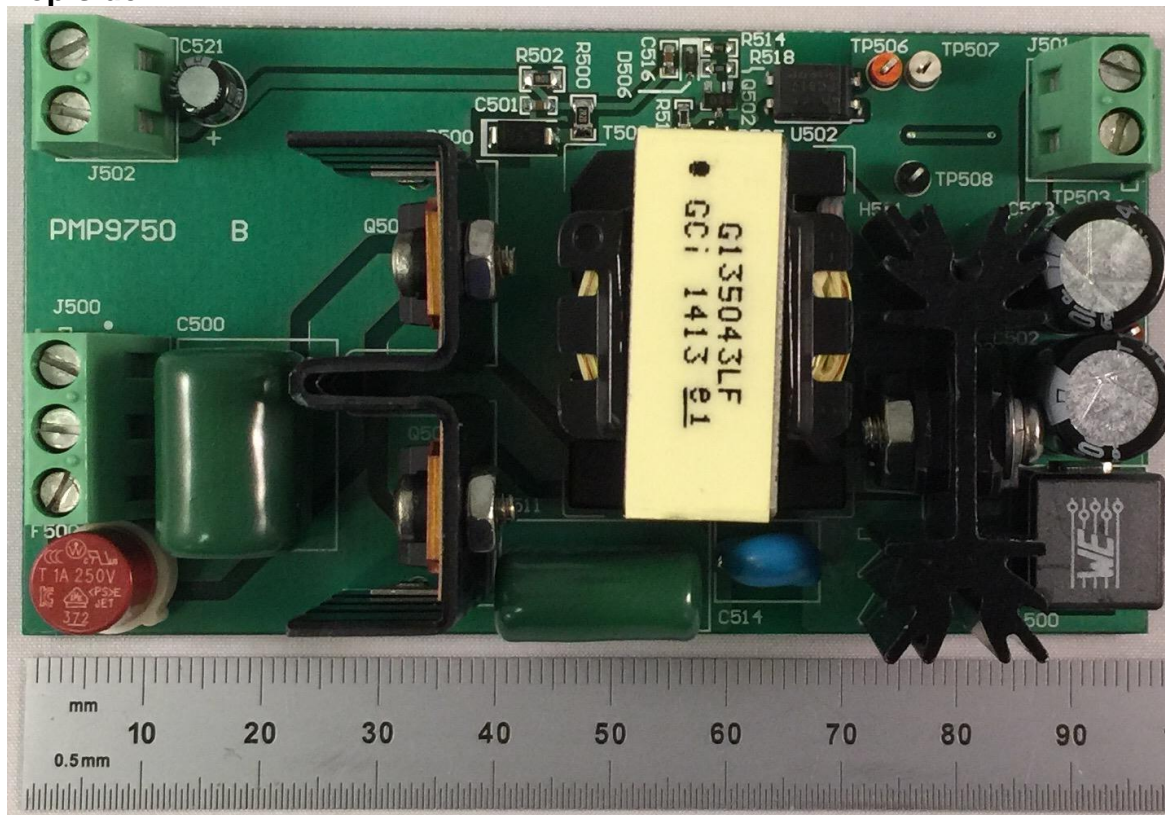


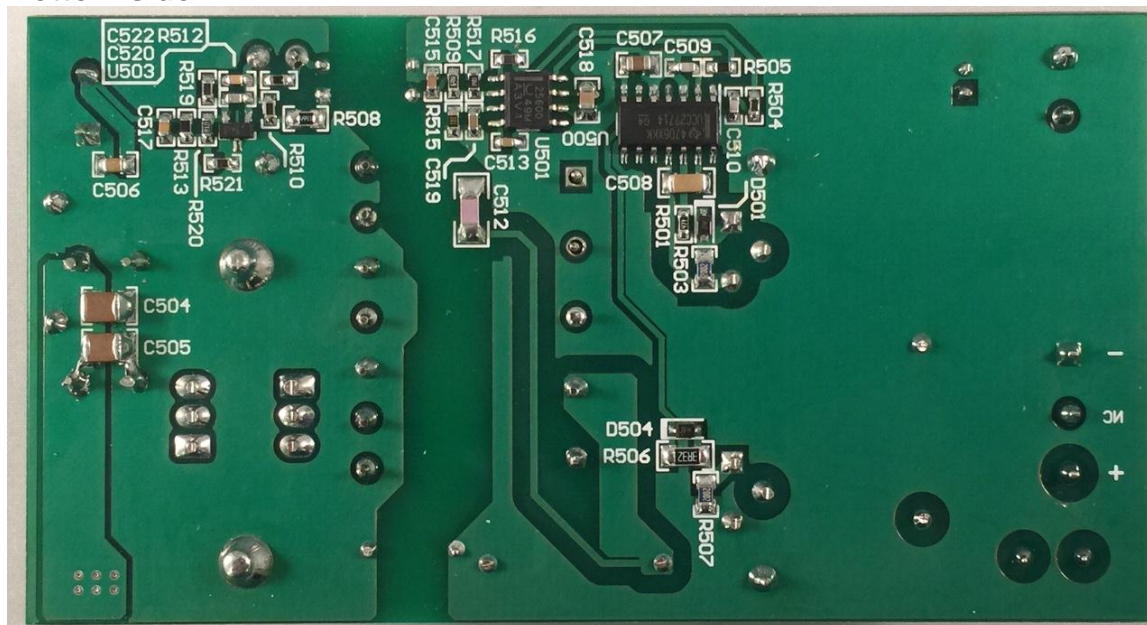
1 Photo

The photographs below show the PMP9750 Rev B assembly. This circuit was built on a PMP9750 Rev B PCB.

Top side



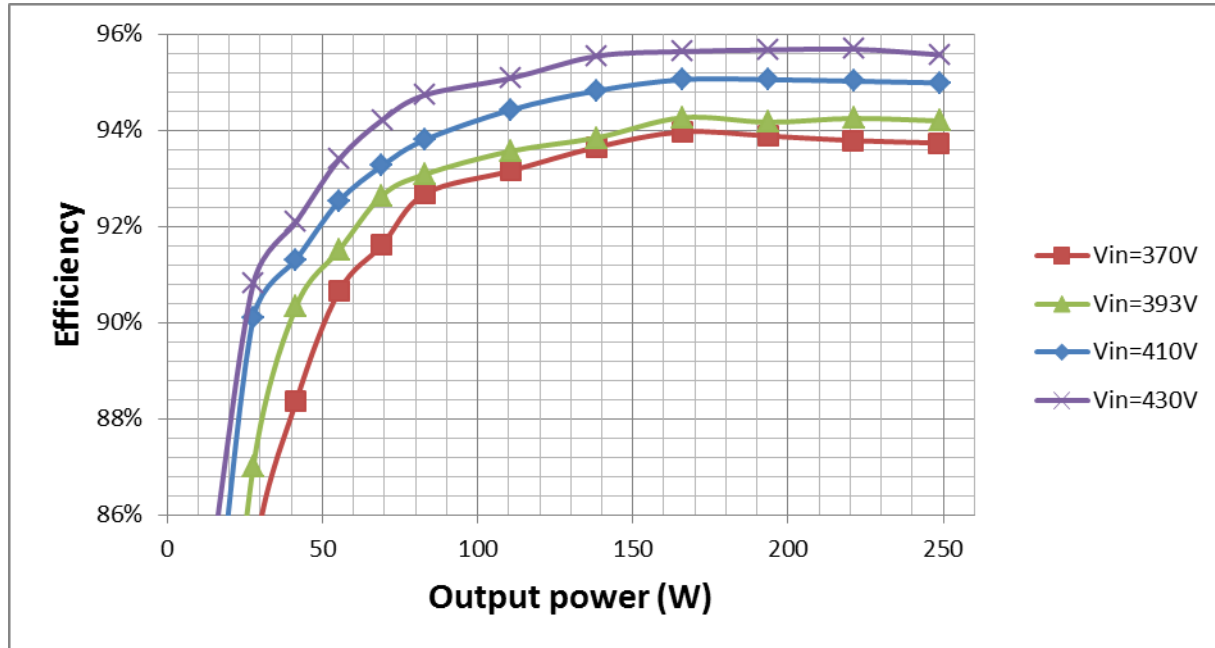
Bottom side



2 Converter Efficiency:

The efficiency curve is shown in the tables and graph below. Driving losses and controller losses from Bias supply are not included here.

2.1 Efficiencies with 28Vout and various input voltages:



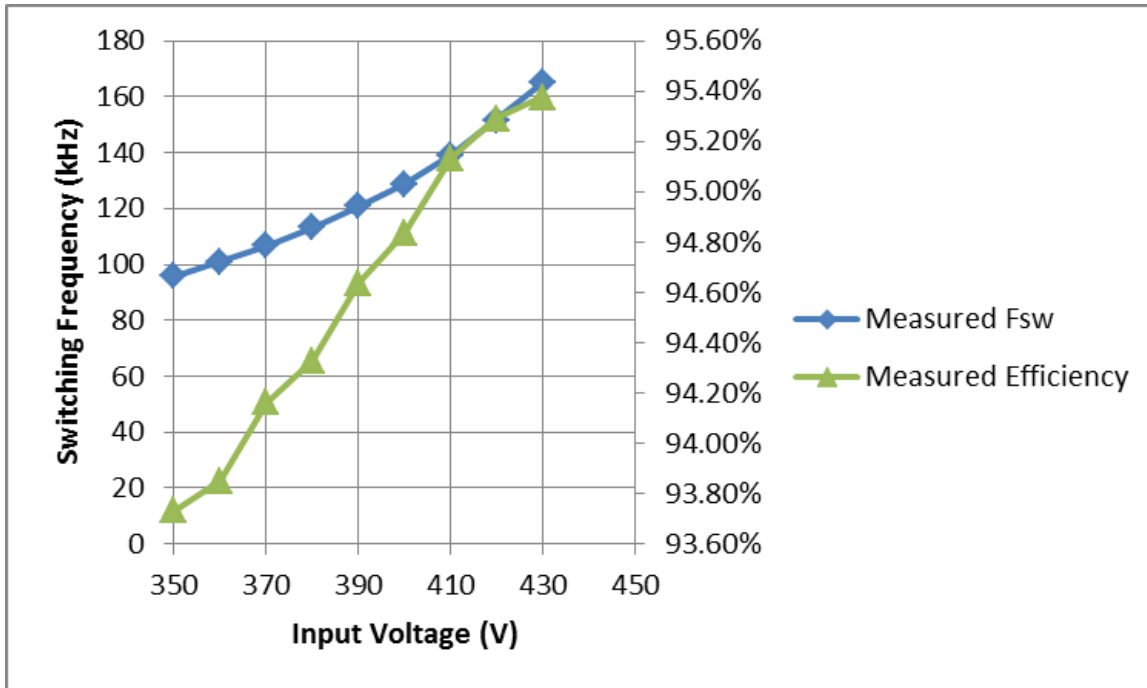
Vin(V)	Iin(A)	Pin(W)	Vout(V)	Iout(A)	Pout(W)	Losses(W)	Efficiency (%)
370	0.717	265.29	27.63	9	248.67	16.62	93.74%
370	0.637	235.69	27.63	8	221.04	14.65	93.78%
370	0.557	206.09	27.64	7	193.48	12.61	93.88%
370	0.477	176.49	27.64	6	165.84	10.65	93.97%
370	0.399	147.63	27.65	5	138.25	9.38	93.65%
370	0.321	118.77	27.66	4	110.64	8.13	93.15%
370	0.242	89.54	27.67	2.999	82.98233	6.55767	92.68%
370	0.204	75.48	27.67	2.499	69.14733	6.33267	91.61%
370	0.165	61.05	27.67	2	55.34	5.71	90.65%
370	0.127	46.99	27.68	1.5	41.52	5.47	88.36%
370	0.088	32.56	27.68	1	27.68	4.88	85.01%
370.1	0.049	18.1349	27.69	0.501	13.87269	4.26221	76.50%
370	0.01	3.7	27.69	0	0	3.7	0.00%

Vin(V)	Iin(A)	Pin(W)	Vout(V)	Iout(A)	Pout(W)	Losses(W)	Efficiency (%)
393	0.672	264.096	27.64	9	248.76	15.336	94.19%
393	0.597	234.621	27.64	8	221.12	13.501	94.25%
393	0.523	205.539	27.65	7	193.55	11.989	94.17%
393	0.448	176.064	27.66	6	165.96	10.104	94.26%
393	0.375	147.375	27.66	5	138.3	9.075	93.84%
393	0.301	118.293	27.67	4	110.68	7.613	93.56%
393	0.227	89.211	27.68	3	83.04	6.171	93.08%
393	0.19	74.67	27.68	2.499	69.17232	5.49768	92.64%
393	0.154	60.522	27.69	2	55.38	5.142	91.50%
393	0.117	45.981	27.69	1.5	41.535	4.446	90.33%
393.1	0.081	31.8411	27.7	1	27.7	4.1411	86.99%
393.1	0.045	17.6895	27.7	0.5	13.85	3.8395	78.30%
393.1	0.005	1.9655	27.74	0	0	1.9655	0.00%

Vin(V)	Iin(A)	Pin(W)	Vout(V)	Iout(A)	Pout(W)	Losses(W)	Efficiency (%)
410	0.639	261.99	27.65	9	248.85	13.14	94.98%
410	0.568	232.88	27.66	8	221.28	11.6	95.02%
410	0.497	203.77	27.67	7	193.69	10.08	95.05%
410	0.426	174.66	27.67	6	166.02	8.64	95.05%
410	0.356	145.96	27.68	5	138.4	7.56	94.82%
410	0.286	117.26	27.68	4	110.72	6.54	94.42%
410	0.216	88.56	27.69	3	83.07	5.49	93.80%
410.1	0.181	74.2281	27.69	2.5	69.225	5.0031	93.26%
410.1	0.146	59.8746	27.7	2	55.4	4.4746	92.53%
410.1	0.111	45.5211	27.71	1.5	41.565	3.9561	91.31%
410.1	0.075	30.7575	27.71	1	27.71	3.0475	90.09%
410.1	0.041	16.8141	27.71	0.501	13.88271	2.93139	82.57%
410.1	0.005	2.0505	27.79	0	0	2.0505	0.00%

Vin(V)	Iin(A)	Pin(W)	Vout(V)	Iout(A)	Pout(W)	Losses(W)	Efficiency (%)
430	0.606	260.58	27.67	9	249.03	11.55	95.57%
430	0.538	231.34	27.67	8	221.36	9.98	95.69%
430	0.471	202.53	27.68	7	193.76	8.77	95.67%
430	0.404	173.72	27.69	6	166.14	7.58	95.64%
430	0.337	144.91	27.69	5	138.45	6.46	95.54%
430	0.271	116.53	27.7	4	110.8	5.73	95.08%
430	0.204	87.72	27.7	3	83.1	4.62	94.73%
430	0.171	73.53	27.71	2.5	69.275	4.255	94.21%
430	0.138	59.34	27.71	2	55.42	3.92	93.39%
430	0.105	45.15	27.72	1.5	41.58	3.57	92.09%
430.1	0.071	30.5371	27.73	1	27.73	2.8071	90.81%
430.1	0.038	16.3438	27.74	0.5	13.87	2.4738	84.86%
430.1	0.002	0.8602	27.84	0	0	0.8602	0.00%

2.2 Efficiencies and switching frequencies with 28Vout/9A and various input voltages:

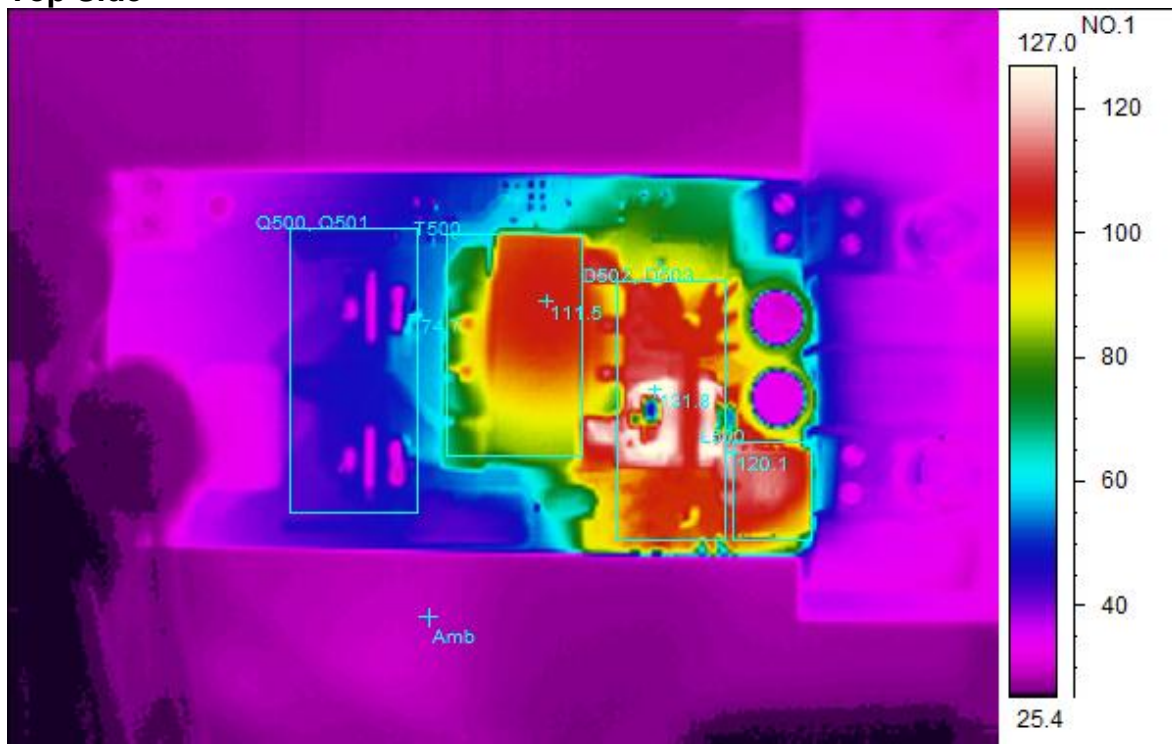


Vin(V)	Iin(A)	Pin(W)	Vout(V)	Iout(A)	Pout(W)	Losses(W)	Efficiency (%)
430	0.607	261.01	27.66	9	248.94	12.07	95.38%
420	0.622	261.24	27.66	9	248.94	12.3	95.29%
410	0.638	261.58	27.65	9	248.85	12.73	95.13%
400	0.656	262.4	27.65	9	248.85	13.55	94.84%
390	0.674	262.86	27.64	9	248.76	14.1	94.64%
380	0.694	263.72	27.64	9	248.76	14.96	94.33%
370	0.714	264.18	27.64	9	248.76	15.42	94.16%
360	0.736	264.96	27.63	9	248.67	16.29	93.85%
350	0.758	265.3	27.63	9	248.67	16.63	93.73%

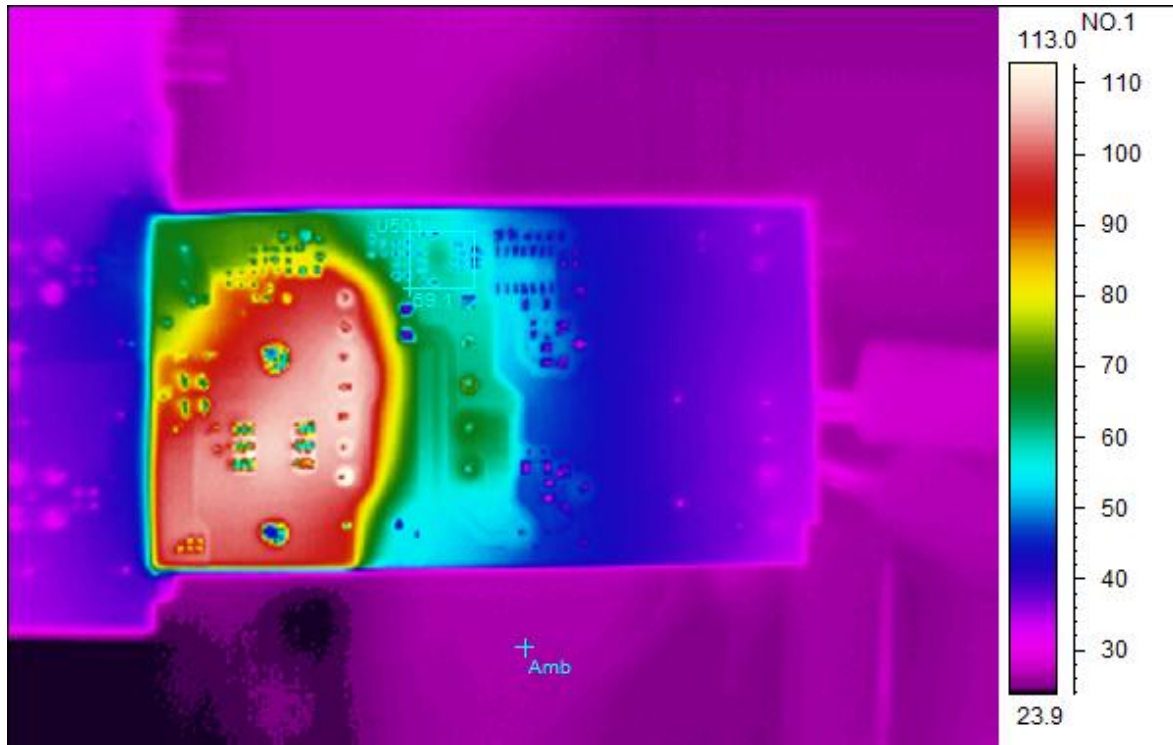
3 Thermal Images

The thermal images below show a top view and bottom view of the board. The thermal images are taken after the board was powered for over 30min. with 20°C ambient temperature and no forced air flow. The input voltage is at 380V and output was loaded with 28V/9A.

Top Side



Spot analysis	Value
Amb Temperature	30.8°C
Area analysis	Value
T500Max	111.5°C
D502, D503Max	131.8°C
L500Max	120.1°C
Q500, Q501Max	74.7°C

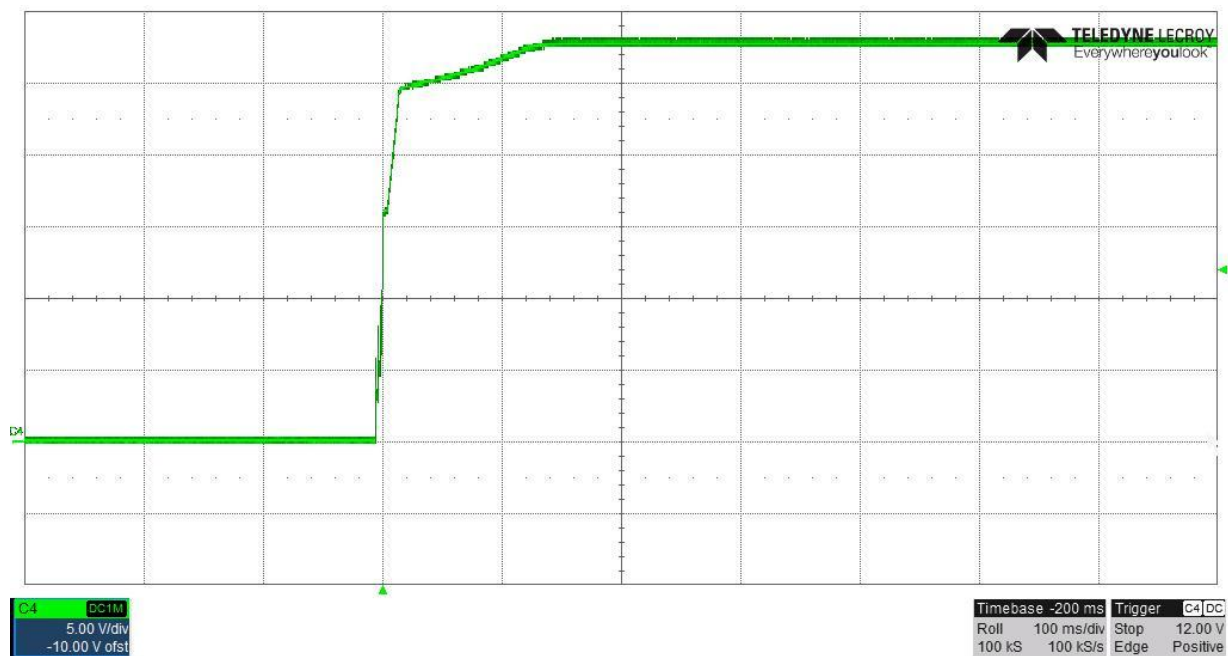
Bottom Side

Spot analysis	Value
Amb Temperature	27.3°C
Area analysis	Value
U501Max	69.1°C

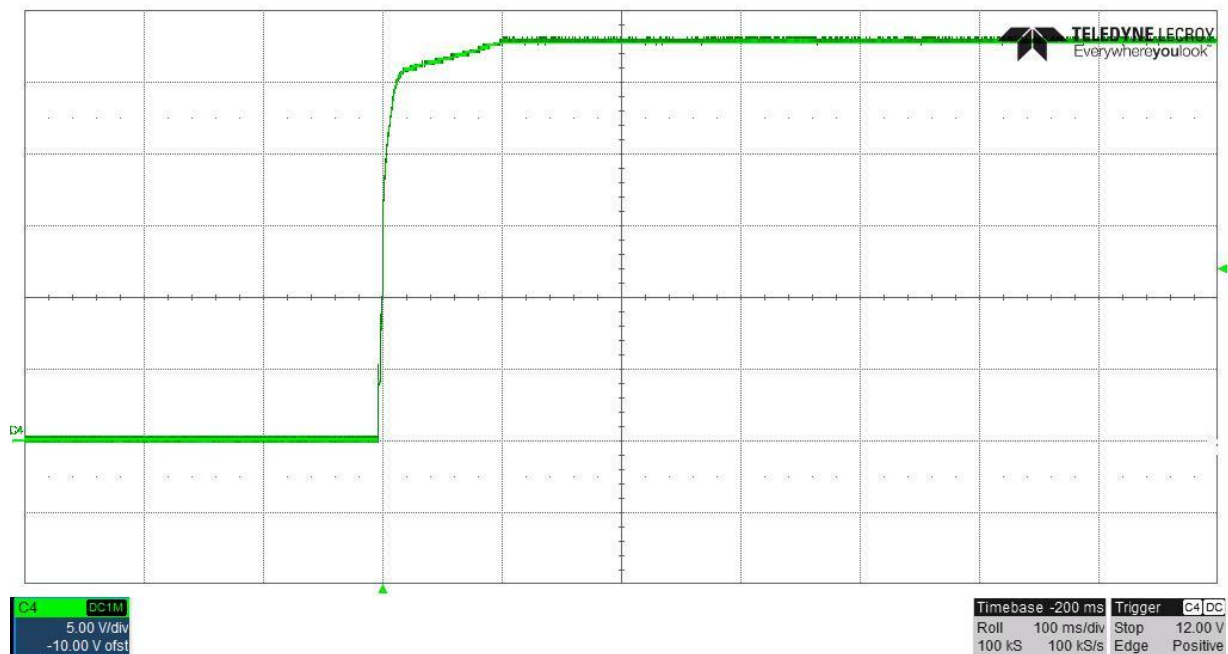
4 Startup

The input/output voltages at startup are shown in the images below, where CH2: V_{in} , CH3: $85V_{OUT}$, CH4: $28V_{OUT}$.

4.1 Start Up @ $380V_{in}$, $28V/9A$:



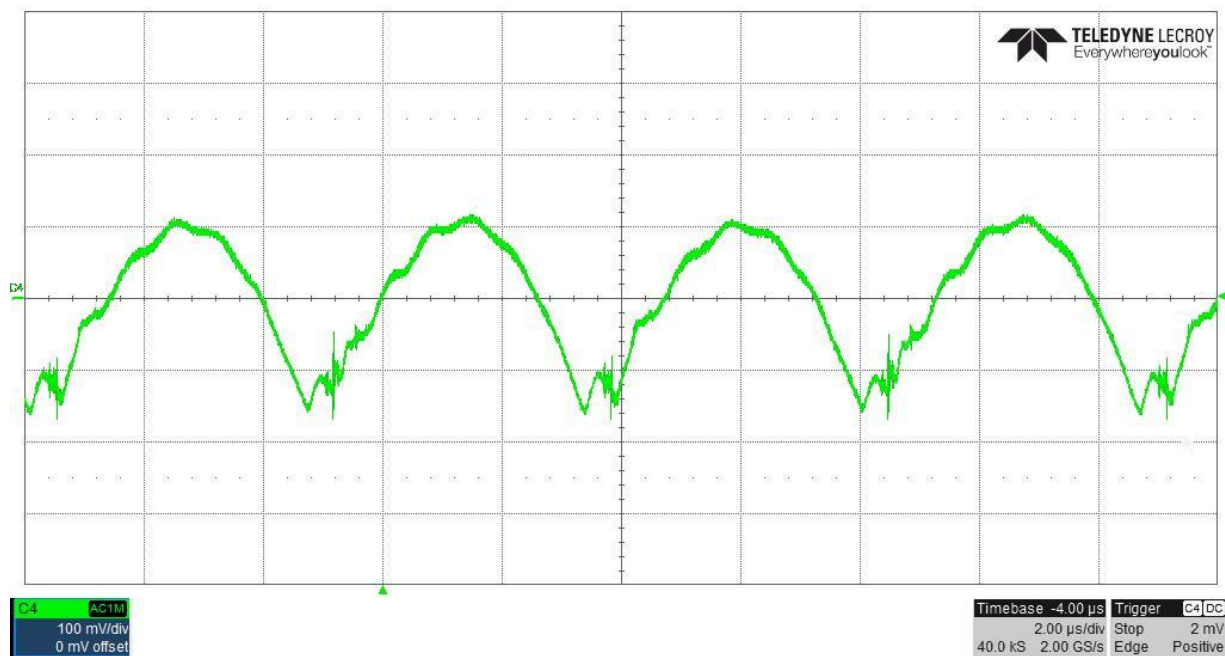
4.2 Start Up @ $380V_{in}$, $28V/0A$:



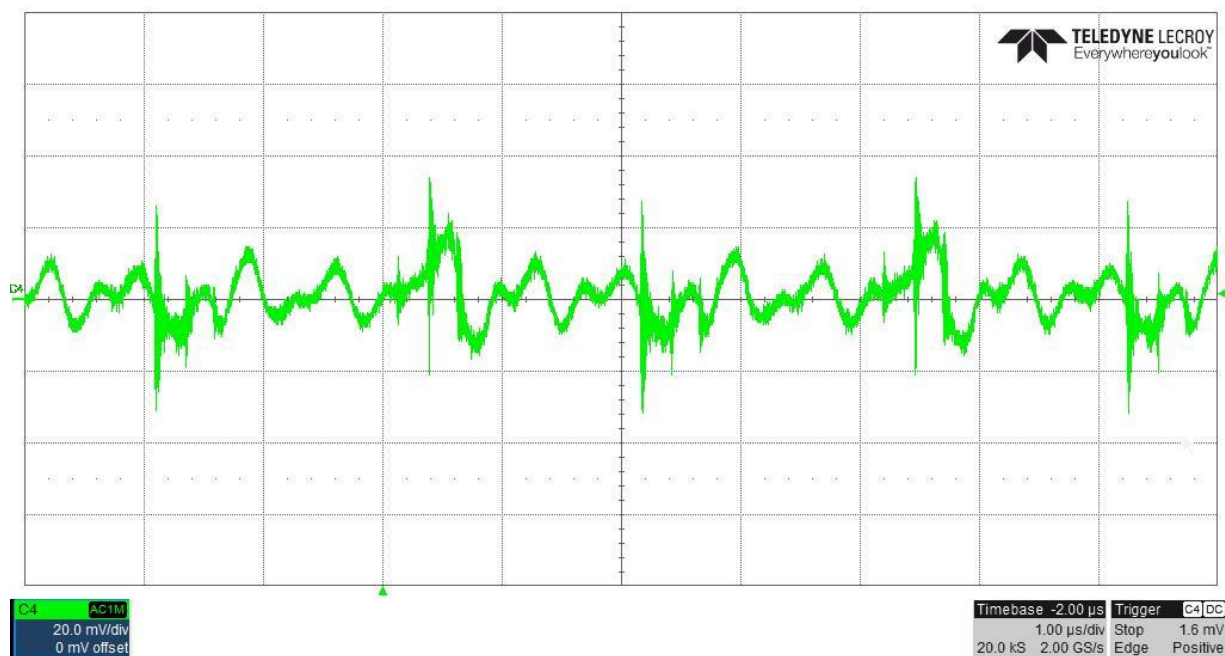
5 Output Ripple Voltages

The output ripple voltages are shown in the plots below with 380V_{DC} input.
CH4: 28V.

5.1 Output ripples @ 28V/9A

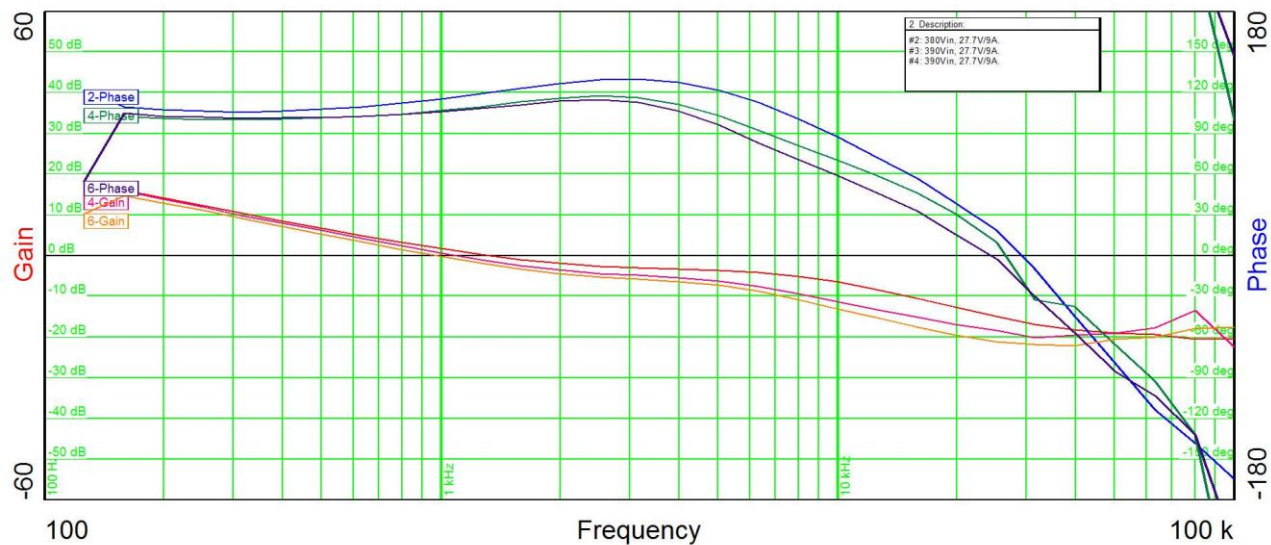


5.2 Output ripples @ 28V/0A



6 Frequency Response

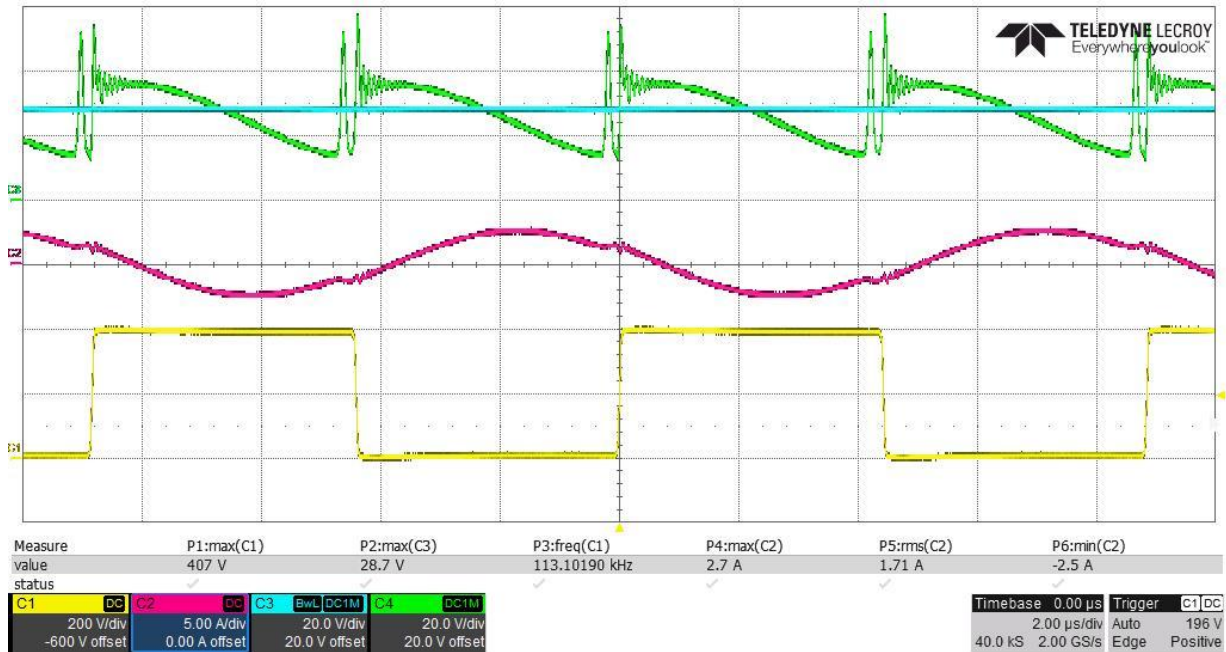
Frequency responses of PMP9750 were measured at 28V/9A output.



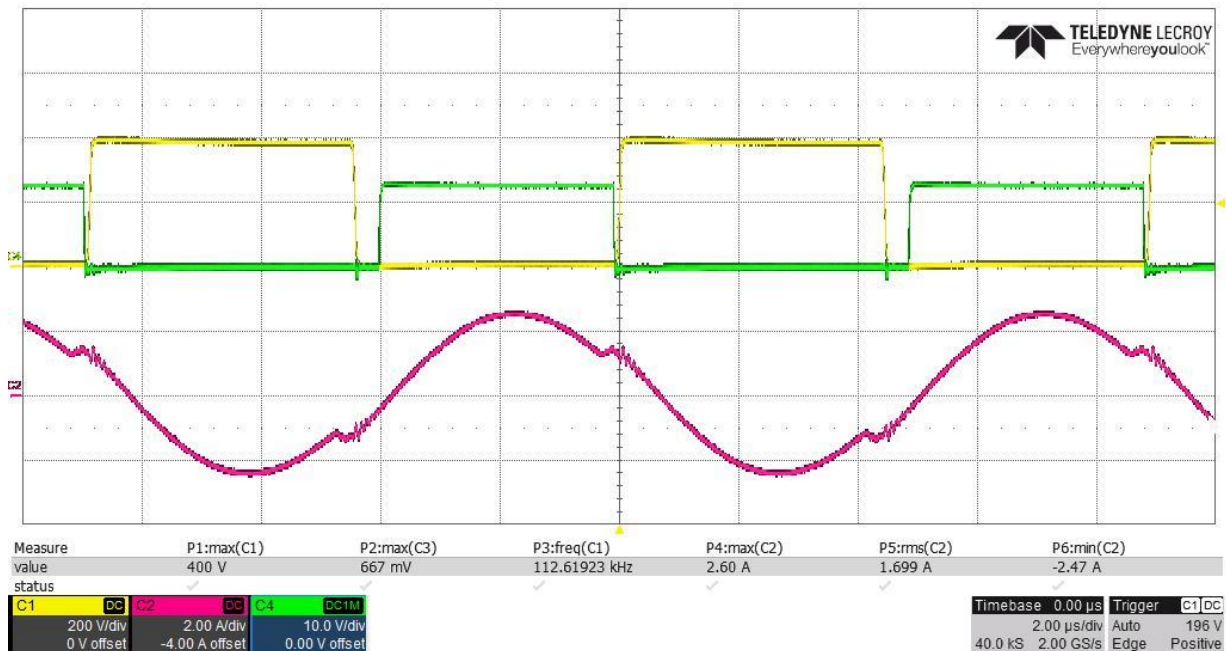
7 Switching Waveforms

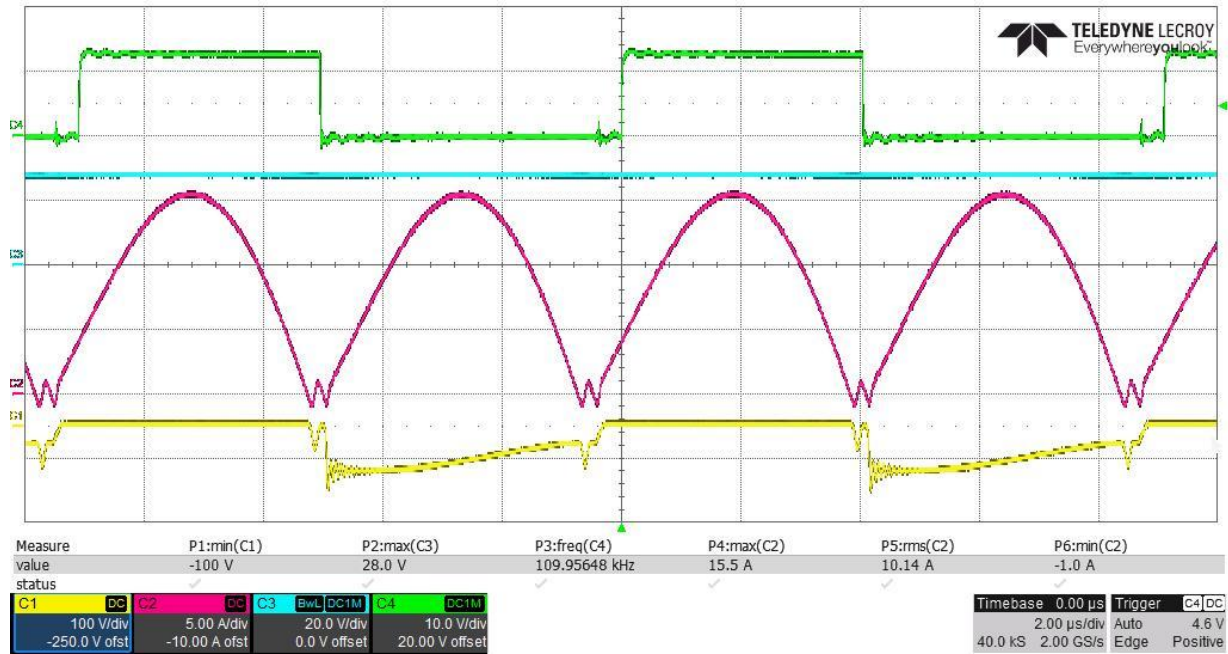
The switching waveforms are shown in the plots below with 380V_{DC} input and 28V/9A output.

7.1 CH1: Q501 V_{DS}, CH2: C511 Current, CH3: V_{out}, CH4: V_{sec to GND} (Voltage after D502 & D503 rectifier).



7.2 CH1: Q501 V_{DS}, CH2: C511 Current, CH4: Q501 V_{GS}.



7.3 CH1: D502 (V_{CA}), CH2: L500 Current, CH3: V_{out} CH4: Q501 V_{GS} .

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